



Mini-Circuits

THIN FILM SURFACE MOUNT

Bandpass Filter

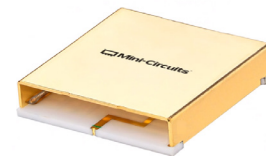
ABF-3R3G+

50Ω

3100 to 3500 MHz

KEY FEATURES

- Low Passband Insertion Loss of 1.6 dB Typ.
- High Rejection of 54 dB Typ.
- Good Return Loss of 15 dB Typ.
- Small Size, 12 x 12 x 2.54 mm



Generic photo used for illustration purposes only

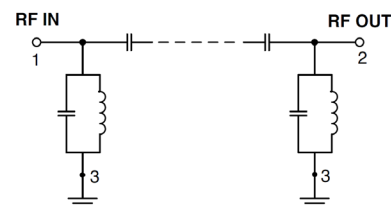
APPLICATIONS

- 5G-sub GHz
- S-Band Radar
- Defense System
- Test and Measurement Equipment

PRODUCT OVERVIEW

Mini-Circuits' Surface Mount Thin-Film filters offer low insertion loss and high rejection realized via Thin-Film on Alumina substrate, using a sputtering process that can guarantee an enhanced Q and repeatable performance. Low pass, high pass, and bandpass surface mount thin-film designs can be realized with this technology up to 40 GHz in a small form factor helping customers achieve their SWaP objectives. Using our high quality thin-film manufacturing process we can guarantee repeatability on large batches of filters.

FUNCTIONAL DIAGRAM

ELECTRICAL SPECIFICATIONS^{1,2,3} AT +25°C

Parameter		F#	Frequency (MHz)	Min.	Typ.	Max.	Units
Passband	Center Frequency ⁴	—	—	—	3300	—	MHz
	Insertion Loss	F1-F2	3100 - 3500	—	1.6	2.5	dB
	Return Loss	F1-F2	3100 - 3500	—	15	—	dB
Stopband, Lower	Rejection	DC-F3	DC - 1500	42	54	—	dB
		F3-F4	1500 - 2400	22	35	—	
Stopband, Upper	Rejection	F5-F6	4000 - 4500	22	44	—	dB
		F6-F7	4500 - 6000	40	50	—	
		F7-F8	6000 - 7000	—	35	—	

1. Measured on Mini-Circuits Characterization Test Board TB-ABF-3R3G+ with feedline losses removed by normalization of S12 and S21 traces to measurement of TB thru-line.

2. This filter is bi-directional RF1 and RF2 ports may be interchanged, see S-Parameters for actual performance.

3. This component is not intended for use as a DC-blocking circuit element. In applications where DC voltage and/or current is present at either the input or output ports, external DC blocking capacitors are required.

4. Typical variation ±3%

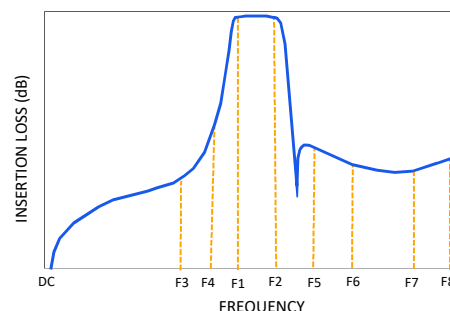
ABSOLUTE MAXIMUM RATINGS⁵

Parameter	Ratings
Operating Temperature	-55 °C to +125 °C
Storage Temperature	-55 °C to +125 °C
Input Power ⁶	12W max. at 25°C

5. Permanent damage may occur if any of these limits are exceeded.

6. Power rating applies only to signals within the passband.

TYPICAL FREQUENCY RESPONSE AT +25°C



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REV. B
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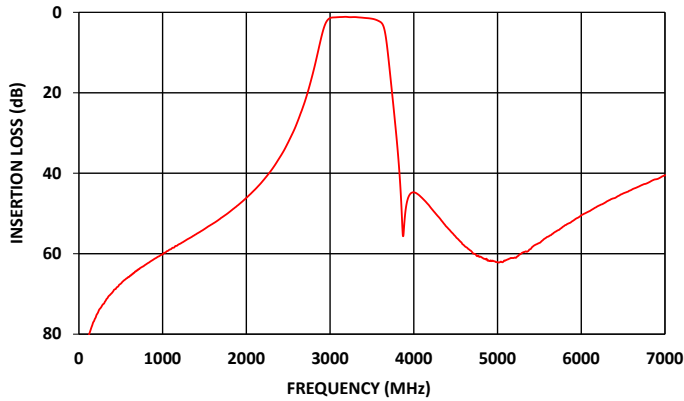
ABF-3R3G+

50 Ω

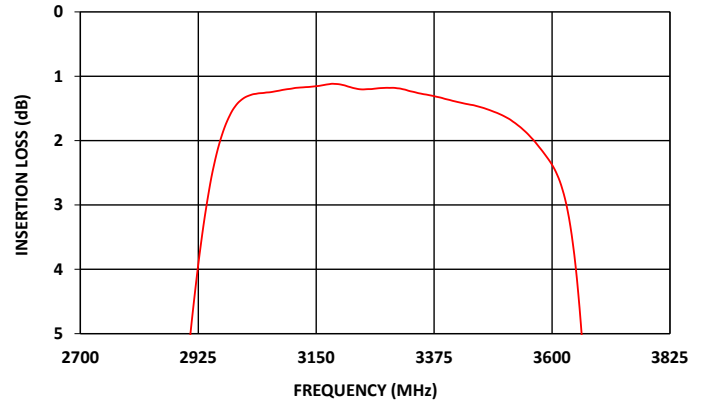
3100 to 3500 MHz

TYPICAL PERFORMANCE GRAPHS AT +25°C

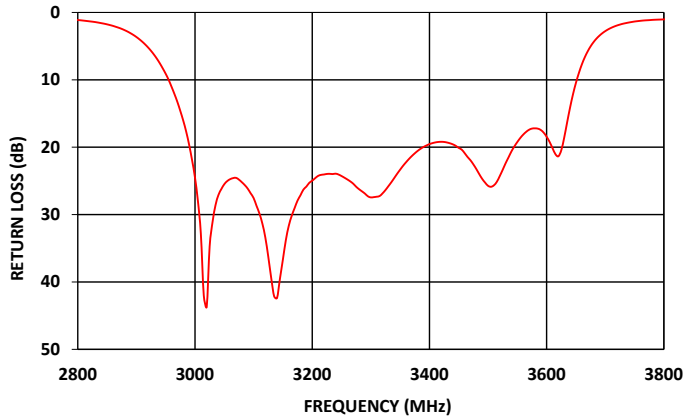
ABF-3R3G+
INSERTION LOSS



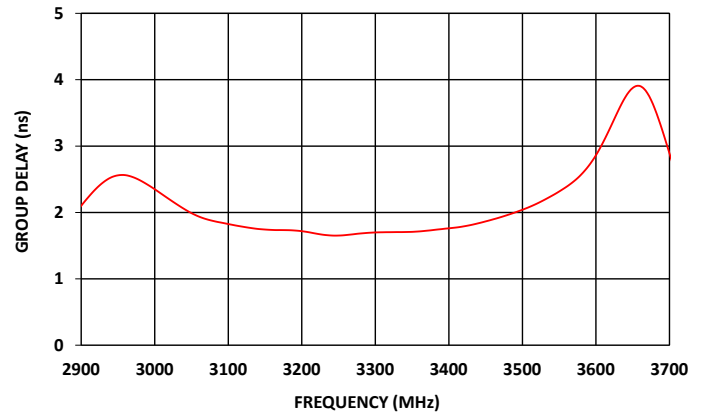
ABF-3R3G+
INSERTION LOSS (Zoomed)



ABF-3R3G+
RETURN LOSS



ABF-3R3G+
GROUP DELAY





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The diagram shows a two-port network. The input port is labeled 'RF IN' and has terminals 1 and 2. The output port is labeled 'RF OUT' and has terminals 3 and 4. Between the input and output ports, there are two parallel LC resonant circuits. The first circuit is connected between terminals 1 and 2, and the second circuit is connected between terminals 3 and 4. Each circuit consists of a capacitor and an inductor in parallel, with a ground connection at the bottom terminal of each circuit.

PAD DESCRIPTION

Function	Pad Number	Description
RF1 ^(Note 2)	1	Connects to RF Input Port
RF2 ^(Note 2)	2	Connects to RF Output Port
GROUND	3	Connects to Ground on PCB, (See drawing PL-755)
NC	—	No connection, not used internally. See drawing PL-755 for connection to PCB

Figure 1: Detailed view of the package footprint. The diagram shows a square footprint with a central array of circular pads. Key dimensions and features include:

- Overall footprint dimensions: .472 inches by .472 inches.
- Central pad array dimensions: .432 inches by .432 inches.
- Pad pitch: 4x.0100±.0005 inch space width.
- Trace width: 2x.0200±.0005 inch.
- Plugged PTH: $\phi .013$ TYP.
- Package outline: Indicated by a dashed line.
- Index: A label pointing to a specific pad.
- PIN 1: A label indicating the location of the first pin.

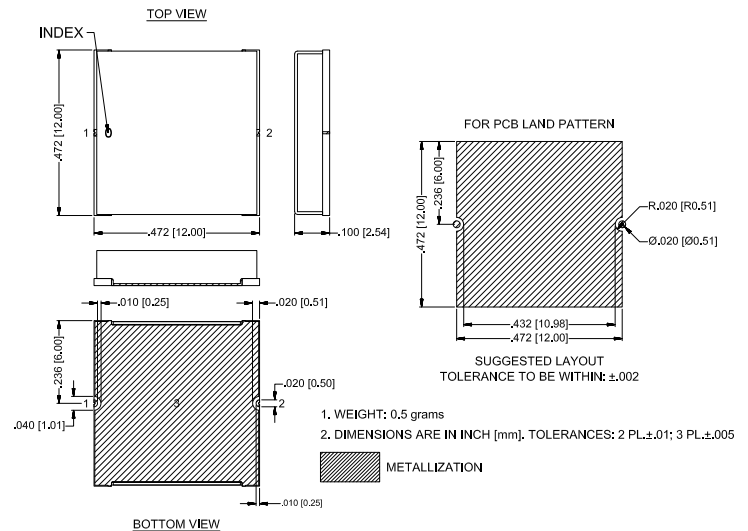
1. COPLANAR WAVEGUIDE PARAMETERS ARE SHOWN FOR ROGERS (RO4350B) WITH DIELECTRIC THICKNESS .010±.001. COPPER: 1/2 Oz. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.

2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.

 DENOTES PCB COPPER PATTERN WITH SMOBC (SOLDER MASK OVER BARE COPPER)

 DENOTES PCB COPPER PATTERN FREE OF SOLDERMASK

CASE STYLE DRAWING



*Marking may contain other features or characters for internal lot control.



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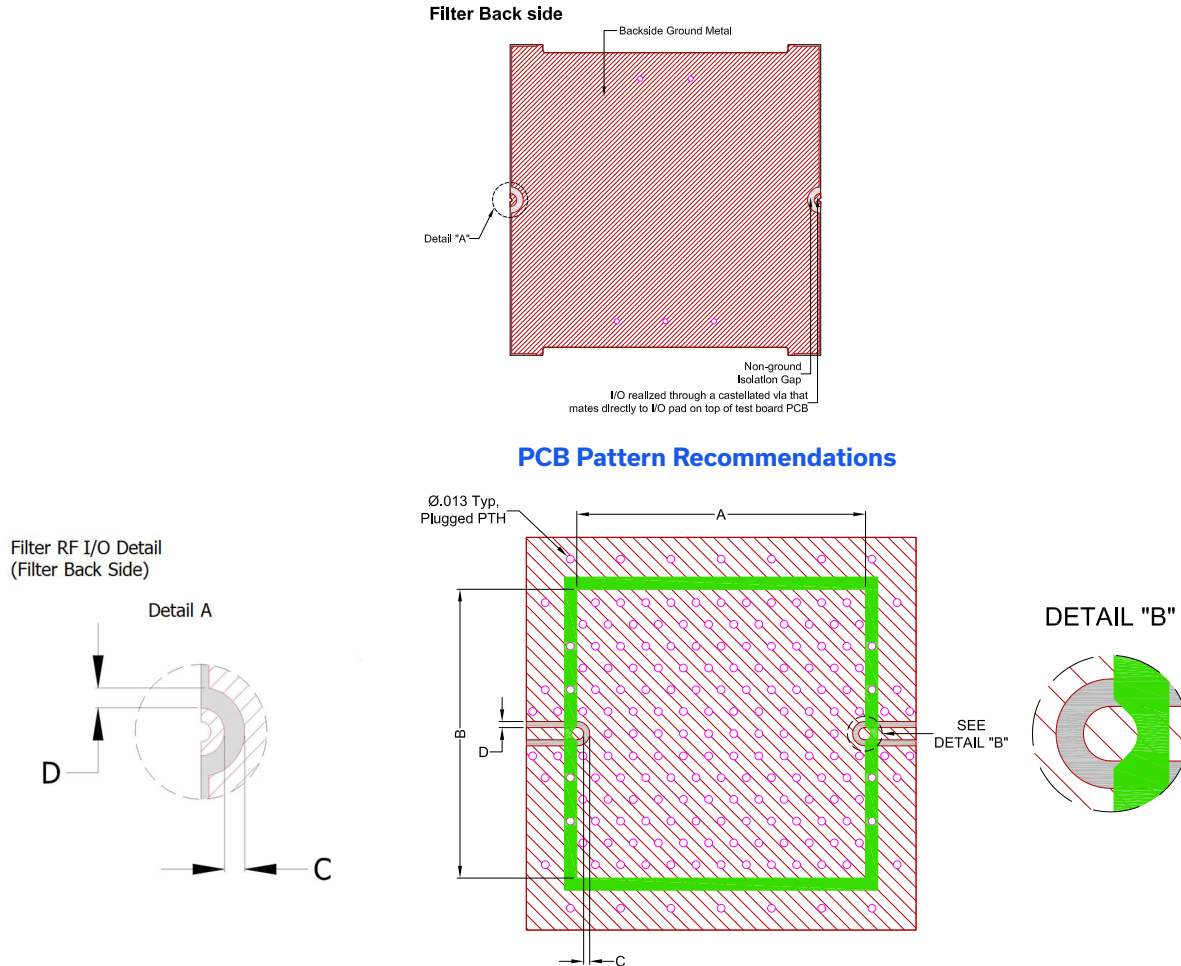
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RECOMMENDED PCB LAYOUT PATTERN FOR FILTER

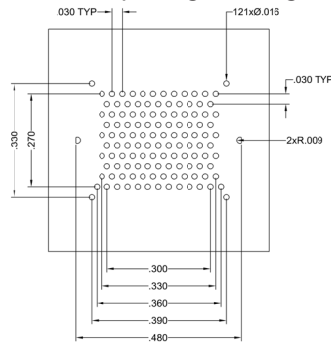


- 1) Customer PCB's ground pattern length (dimension A) can be similar to filter length.
- 2) Customer PCB's ground pattern width (dimension B) can be similar to filter width.
- 3) Dimensions C and D on Filter RF I/O detail and Customer PCB pattern can be closely match. The dimensions of C and D on the Customer PCB pattern can be slightly larger to account for component alignment tolerance (ground metal can be pulled back from RF I/O trace).
- 4) Recommend to use Solder mask at Customer PCB at outer area of filter pattern/ footprint with a clearance of about 1.25mil at each side. (Tighter registration tolerance required for solder mask)
- 5) Recommended to use Solder mask at I/O of Customer PCB as per above diagram (refer detail B).

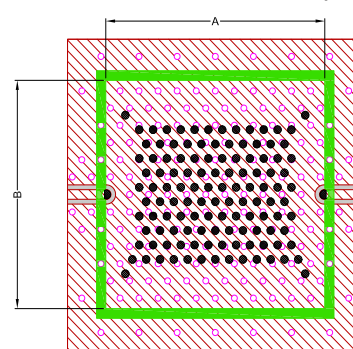
**COMMENTS ON COMPONENT HANDLING AND SOLDER ATTACH**

- 1) Avoid using soldering iron directly to the ceramic filter. This would lead to development of crack in the component due to thermal shock.
- 2) Vacuum pick-up tool or plastic tweezers are recommended for handling the components. Extra care should be taken not to scratch the filter or metal area.
- 3) Use 2-3 mil thickness stencil plate and screen print the solder. Refer below picture for recommended stencil pattern to get the best solder attachment.

Stencil opening drawing



Solder location after screen print



- 4) Plugged ground vias in the PWB will improve attachment consistency.
- 5) Recommended to have a similar or closer test board material and thickness (refer Mini-Circuits evaluation board for details) to minimize the CTE over the temperature range.



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ADDITIONAL DETAILED INFORMATION IS AVAILABLE ON OUR DASH BOARD.

[CLICK HERE](#)

Performance Data and Graphs	Data
	Graphs
	S-Parameter (S2P Files) Data Set (.zip file) De-embedded to device pads
Case Style	ZH3433 Lead Finish: Gold over Nickel Plate
RoHS Status	Compliant
Tape and Reel	TR-F008
Suggested Layout for PCB Design	PL-755
Evaluation Board	TB-ABF-3R3G+
	Gerber File
Environmental Rating	ENV120T1

NOTES

- A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.
- B. Electrical specifications and performance data contained in this specification document are based on Mini-Circuits' applicable established test performance criteria and measurement instructions.
- C. The parts covered by this specification document are subject to Mini-Circuits' standard limited warranty and terms and conditions (collectively, "Standard Terms"); Purchasers of this part are entitled to the rights and benefits contained therein. For a full statement of the standard terms and the exclusive rights and remedies thereunder, please visit Mini-Circuits' website at www.minicircuits.com/terms/viewterm.html

